

IMPORTANT NOTICE

10 December 2015

1. Global joint venture starts operations as WeEn Semiconductors

Dear customer,

As from November 9th, 2015 NXP Semiconductors N.V. and Beijing JianGuang Asset Management Co. Ltd established Bipolar Power joint venture (JV), **WeEn Semiconductors**, which will be used in future Bipolar Power documents together with new contact details.

In this document where the previous NXP references remain, please use the new links as shown below.

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Thank you for your cooperation and understanding,

WeEn Semiconductors



BTA204W-800E

3Q Hi-Com Triac

15 August 2014

Product data sheet

1. General description

Planar passivated three quadrant guaranteed commutation triac in a SOT223 surface mountable plastic package for use in motor control circuits or with other highly inductive loads. This triac balances the requirements of commutation performance and gate sensitivity and is intended for use with low power drivers, including microcontrollers.

2. Features and benefits

- 3Q technology for improved noise immunity
- Direct triggering from low power drivers and logic ICs
- High commutation capability with sensitive gate
- High immunity to false turn-on by dV/dt with sensitive gate
- Planar passivated for voltage ruggedness and reliability
- Sensitive gate for easy logic level triggering
- Surface mountable package

3. Applications

- General purpose motor controls
- Small loads in washing machines
- Rectifier-fed DC inductive loads e.g. DC motors and solenoids

4. Quick reference data

Table 1. Quick reference data

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
V_{DRM}	repetitive peak off-state voltage			-	-	800	V
I_{TSM}	non-repetitive peak on-state current	full sine wave; $T_{j(\text{init})} = 25^\circ\text{C}$; $t_p = 20 \text{ ms}$; Fig. 4 ; Fig. 5		-	-	10	A
$I_{T(\text{RMS})}$	RMS on-state current	full sine wave; $T_{sp} \leq 108^\circ\text{C}$; Fig. 1 ; Fig. 2 ; Fig. 3		-	-	1	A



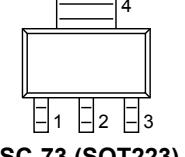
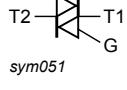
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Symbol	Parameter	Conditions		Min	Typ	Max	Unit
Static characteristics							
I _{GT}	gate trigger current	V _D = 12 V; I _T = 0.1 A; T2+ G+; T _j = 25 °C; Fig. 9		-	-	10	mA
			-	-	10	mA	
			-	-	10	mA	

5. Pinning information

Table 2. Pinning information

Pin	Symbol	Description	Simplified outline	Graphic symbol
1	T1	main terminal 1	 SC-73 (SOT223)	 sym051
2	T2	main terminal 2		
3	G	gate		
4	mb	mounting base; main terminal 2		

6. Ordering information

Table 3. Ordering information

Type number	Package		
	Name	Description	Version
BTA204W-800E	SC-73	plastic surface-mounted package with increased heatsink; 4 leads	SOT223

7. Limiting values

Table 4. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions		Min	Max	Unit
V_{DRM}	repetitive peak off-state voltage			-	800	V
$I_{T(RMS)}$	RMS on-state current	full sine wave; $T_{sp} \leq 108^\circ\text{C}$; Fig. 1 ; Fig. 2 ; Fig. 3		-	1	A
I_{TSM}	non-repetitive peak on-state current	full sine wave; $T_{j(\text{init})} = 25^\circ\text{C}$; t_p 16.7 ms		-	11	A
		full sine wave; $T_{j(\text{init})} = 25^\circ\text{C}$; $t_p = 20$ ms; Fig. 4 ; Fig. 5		-	10	A
I^2t	I^2t for fusing	$t_p = 10$ ms; SIN		-	0.5	A^2s
dI_T/dt	rate of rise of on-state current	$I_T = 1.5$ A; $I_G = 0.2$ A; $dI_G/dt = 0.2$ A/ μs		-	100	$\text{A}/\mu\text{s}$
I_{GM}	peak gate current			-	2	A
P_{GM}	peak gate power			-	5	W
$P_{G(AV)}$	average gate power	over any 20ms period		-	0.5	W
T_{stg}	storage temperature			-40	150	$^\circ\text{C}$
T_j	junction temperature			-	125	$^\circ\text{C}$

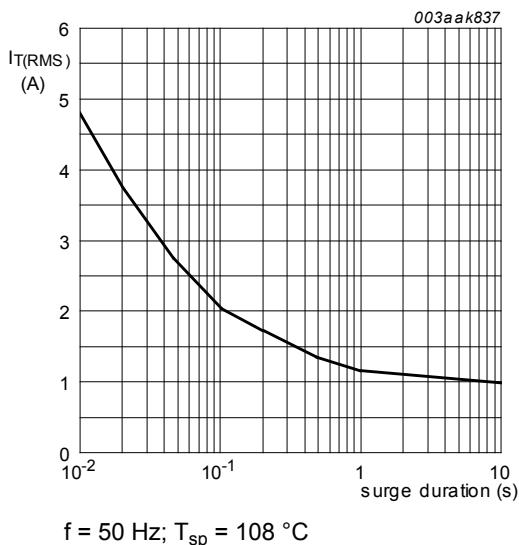


Fig. 1. RMS on-state current as a function of surge duration; maximum values

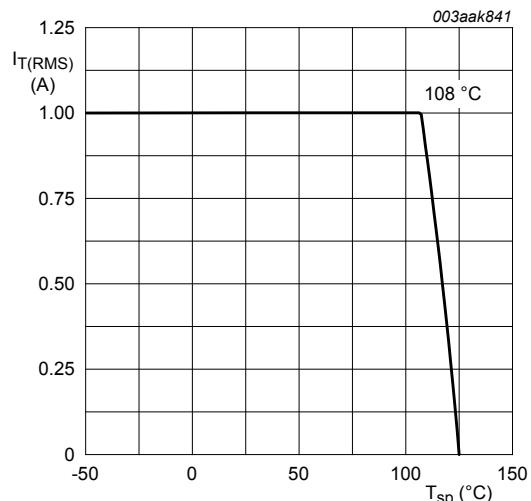


Fig. 2. RMS on-state current as a function of solder point temperature; maximum values

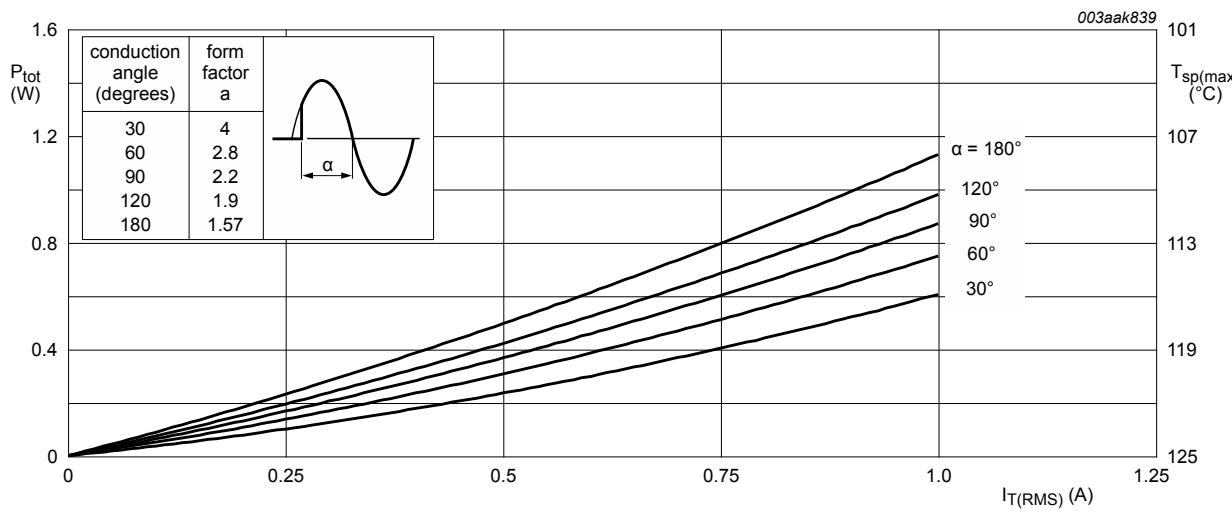


Fig. 3. Total power dissipation as a function of RMS on-state current; maximum values

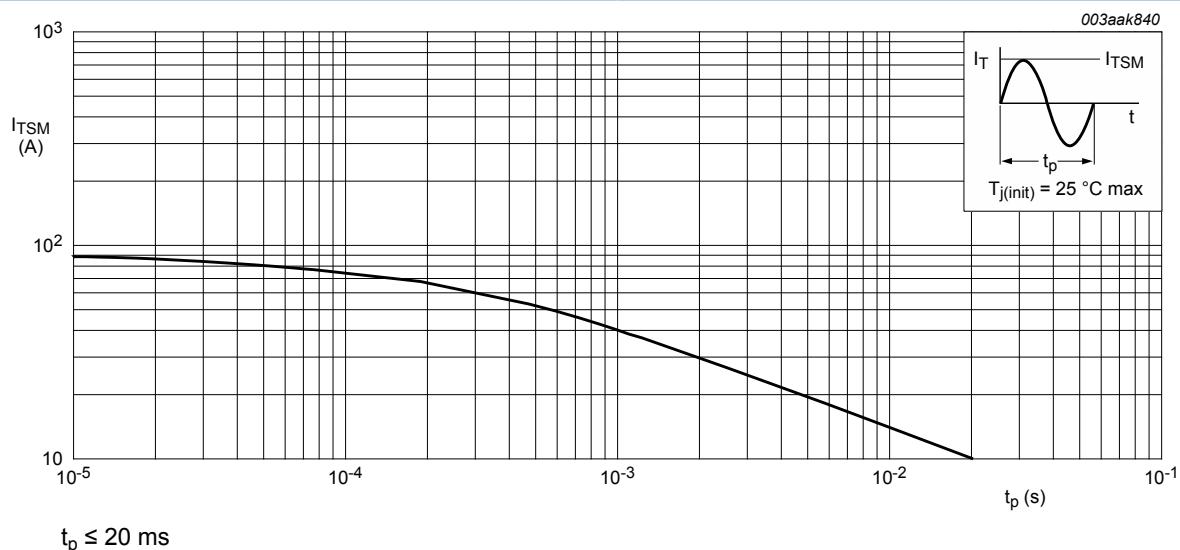
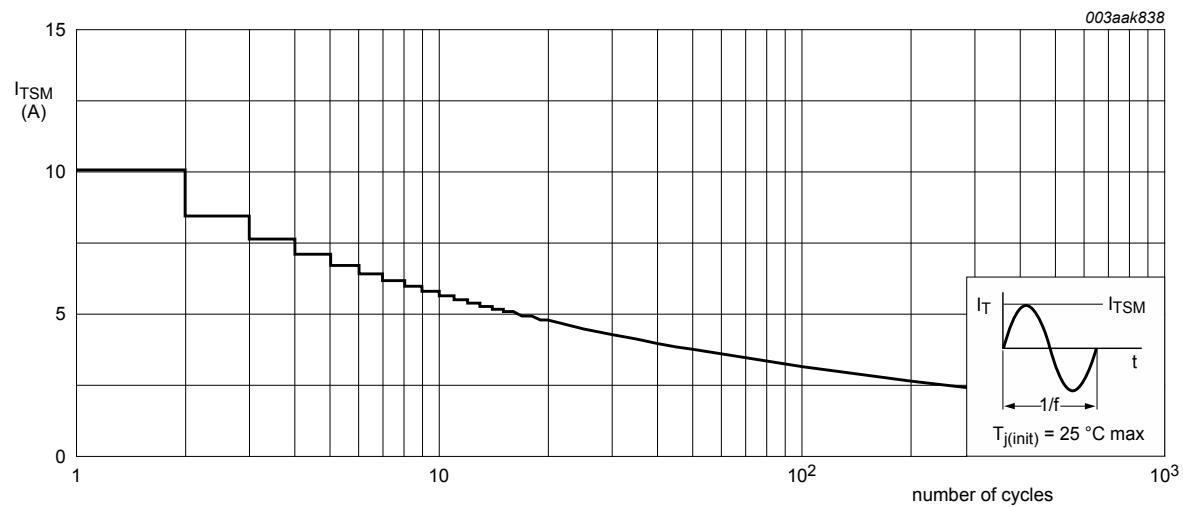


Fig. 4. Non-repetitive peak on-state current as a function of pulse width; maximum values



$f = 50$ Hz

Fig. 5. Non-repetitive peak on-state current as a function of the number of sinusoidal current cycles; maximum values

8. Thermal characteristics

Table 5. Thermal characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$R_{th(j-sp)}$	thermal resistance from junction to solder point	full cycle or half cycle; Fig. 6	-	-	15	K/W
$R_{th(j-a)}$	thermal resistance from junction to ambient	in free air; printed circuit board mounted: minimum pad area; Fig. 7	-	70	-	K/W
		in free air; printed circuit board mounted: minimum footprint; Fig. 8	-	156	-	K/W

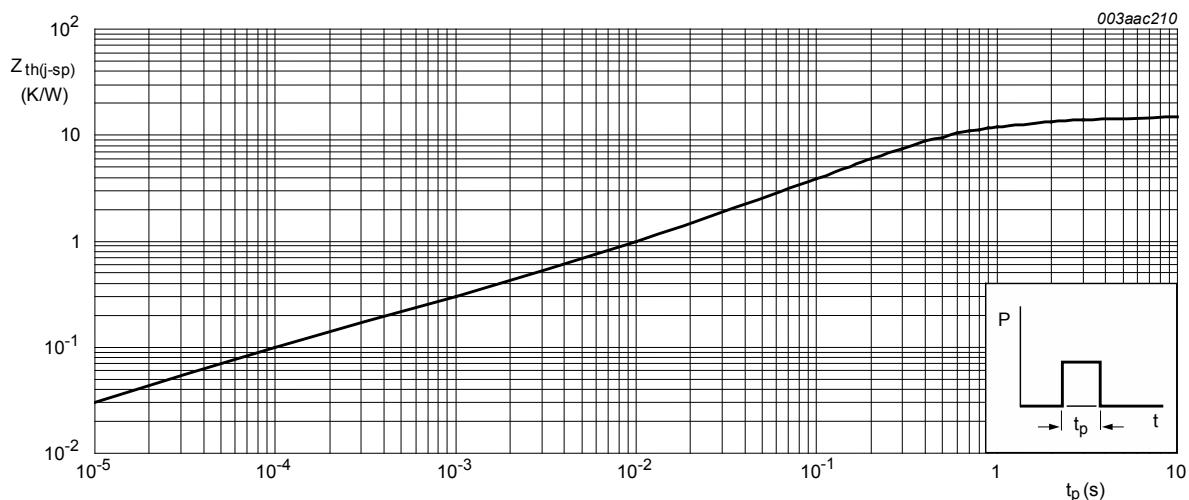
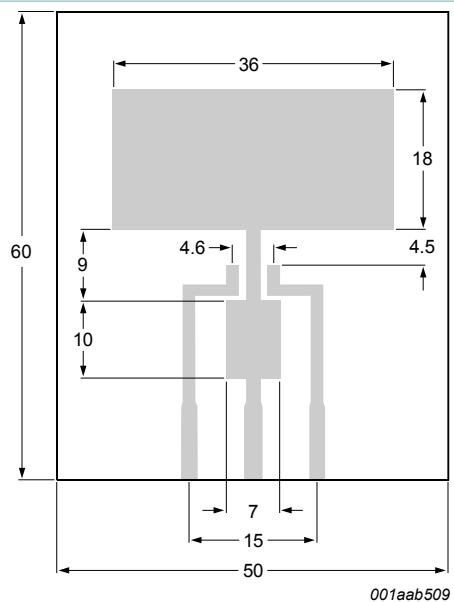


Fig. 6. Transient thermal impedance from junction to solder point as a function of pulse width

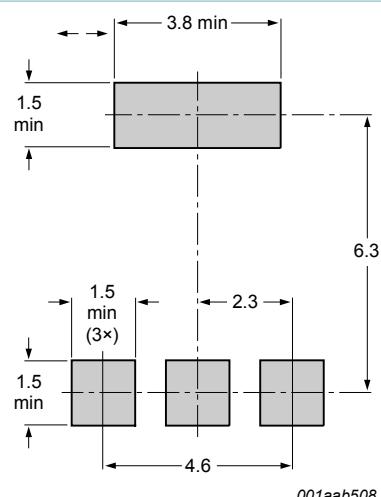


All dimensions are in mm

Printed circuit board:

FR4 epoxy glass (1.6 mm thick), copper laminate
(35 um thick)

Fig. 7. Printed circuit board pad area: SOT223



All dimensions are in mm

Fig. 8. Minimum footprint SOT223

9. Characteristics

Table 6. Characteristics

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
Static characteristics							
I _{GT}	gate trigger current	V _D = 12 V; I _T = 0.1 A; T2+ G+; T _j = 25 °C; Fig. 9		-	-	10	mA
		V _D = 12 V; I _T = 0.1 A; T2+ G-; T _j = 25 °C; Fig. 9		-	-	10	mA
		V _D = 12 V; I _T = 0.1 A; T2- G-; T _j = 25 °C; Fig. 9		-	-	10	mA
I _L	latching current	V _D = 12 V; I _G = 0.1 A; T2+ G-; T _j = 25 °C; Fig. 10		-	-	12	mA
		V _D = 12 V; I _G = 0.1 A; T2+ G+; T _j = 25 °C; Fig. 10		-	-	18	mA
		V _D = 12 V; I _G = 0.1 A; T2- G-; T _j = 25 °C; Fig. 10		-	-	12	mA
I _H	holding current	V _D = 12 V; T _j = 25 °C; Fig. 11		-	-	12	mA
V _T	on-state voltage	I _T = 2 A; T _j = 25 °C; Fig. 12		-	0.7	1.5	V
V _{GT}	gate trigger voltage	V _D = 12 V; I _T = 0.1 A; T _j = 25 °C; Fig. 13		-	0.7	1	V
		V _D = 400 V; I _T = 0.1 A; T _j = 125 °C; Fig. 13		0.25	0.4	-	V
I _D	off-state current	V _D = 800 V; T _j = 125 °C		-	0.1	0.5	mA
Dynamic characteristics							
dV _D /dt	rate of rise of off-state voltage	V _{DM} = 536 V; T _j = 125 °C; (67% of V _{DRM}); exponential waveform; gate open circuit		30	-	-	V/μs
dI _{com} /dt	rate of change of commutating current	V _D = 400 V; T _j = 125 °C; I _{T(RMS)} = 1 A; dV _{com} /dt = 20 V/μs; (snubberless condition); gate open circuit		2	-	-	A/ms

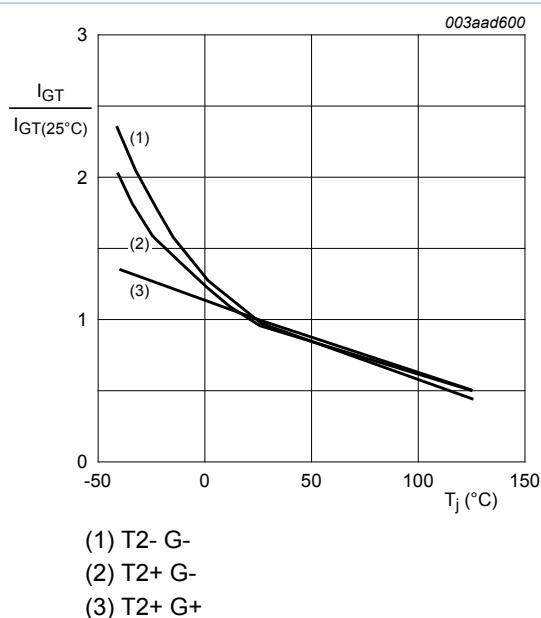


Fig. 9. Normalized gate trigger current as a function of junction temperature

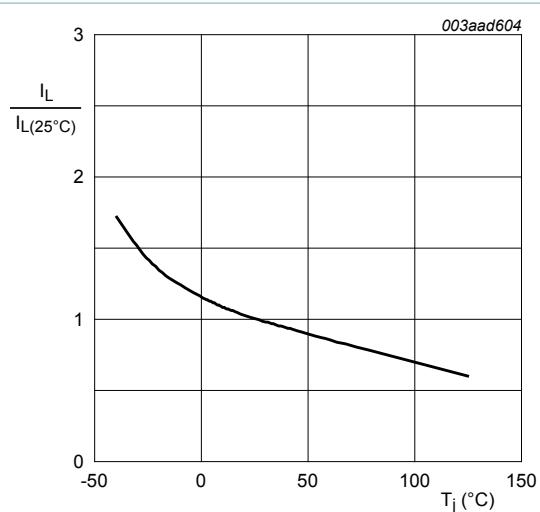


Fig. 10. Normalized latching current as a function of junction temperature

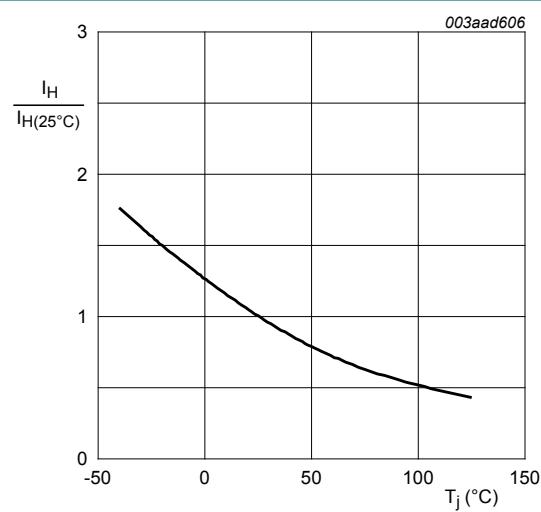


Fig. 11. Normalized holding current as a function of junction temperature

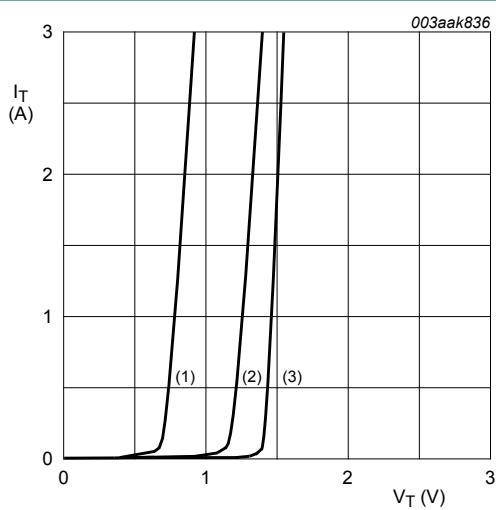


Fig. 12. On-state current as a function of on-state voltage

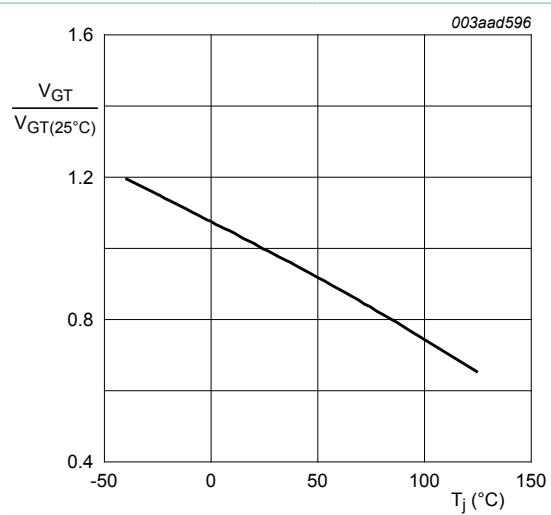


Fig. 13. Normalized gate trigger voltage as a function of junction temperature

10. Package outline

Plastic surface-mounted package with increased heatsink; 4 leads

SOT223

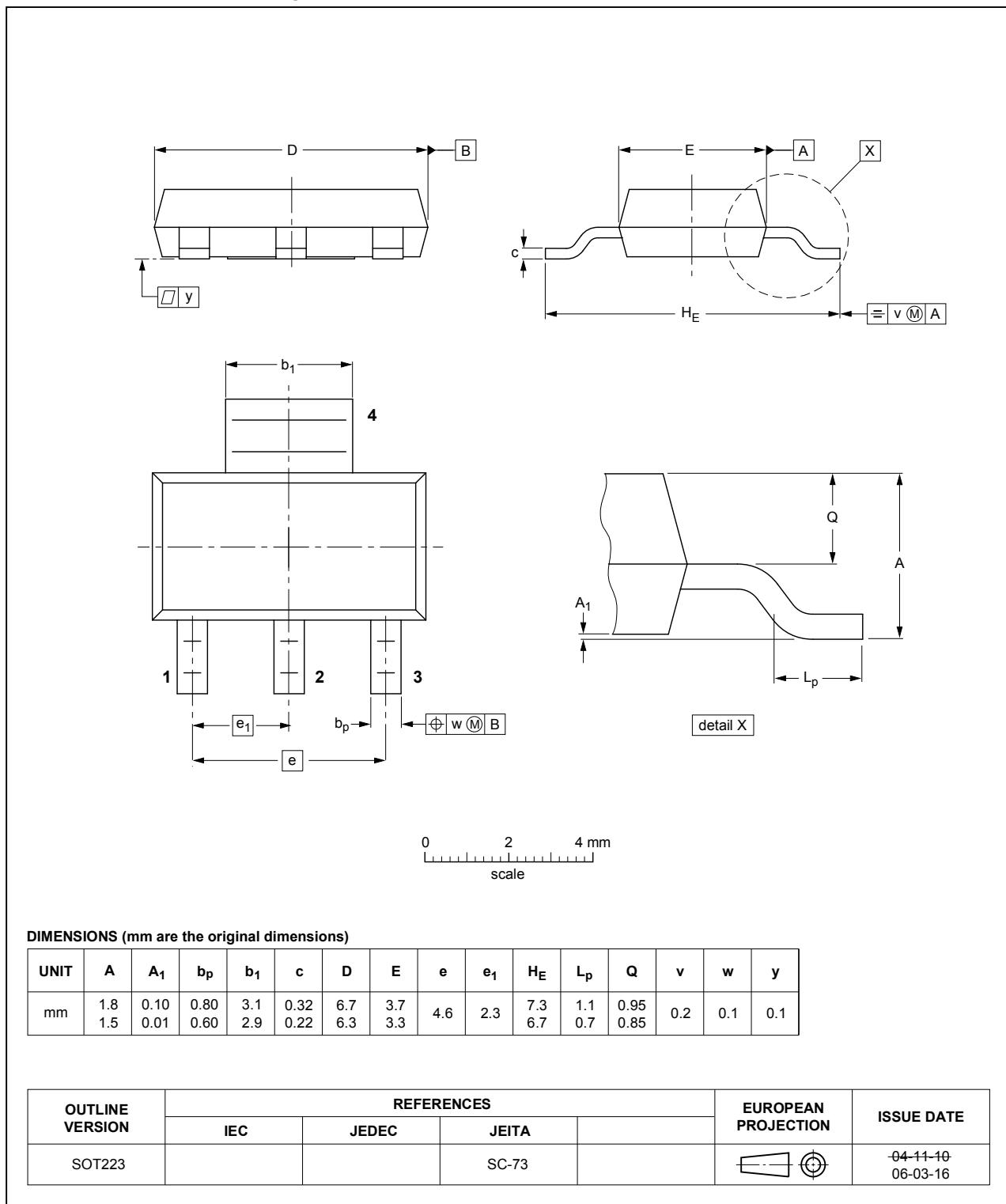


Fig. 14. Package outline SC-73 (SOT223)

11. Soldering

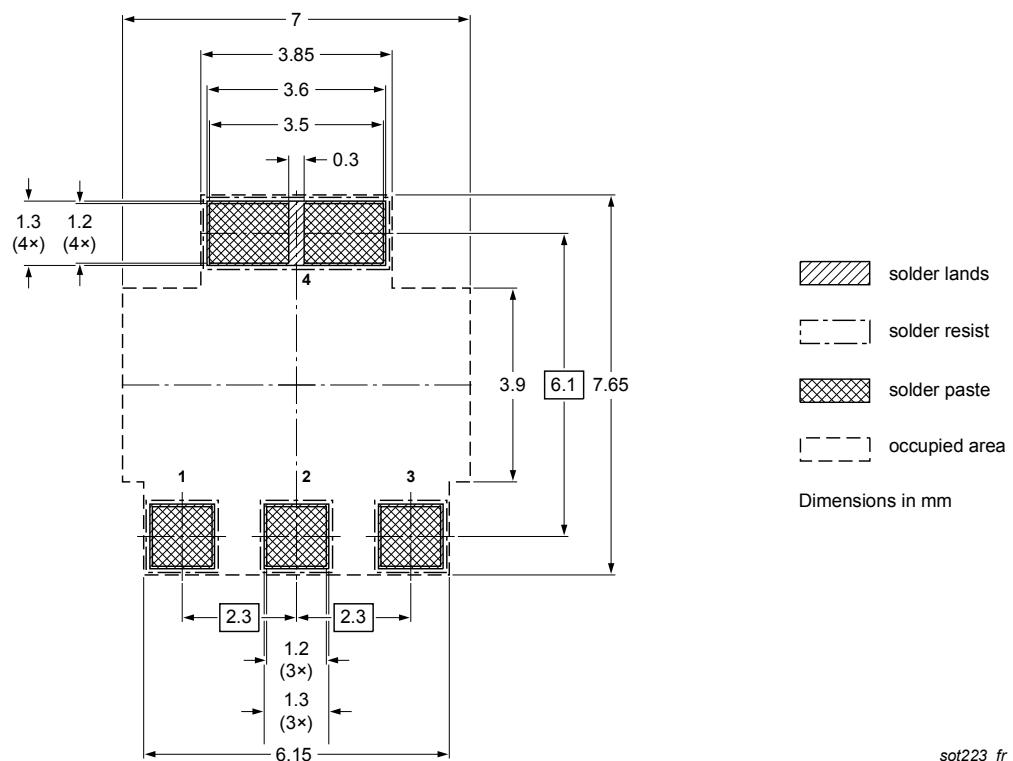


Fig. 15. Reflow soldering footprint for SC-73 (SOT223)

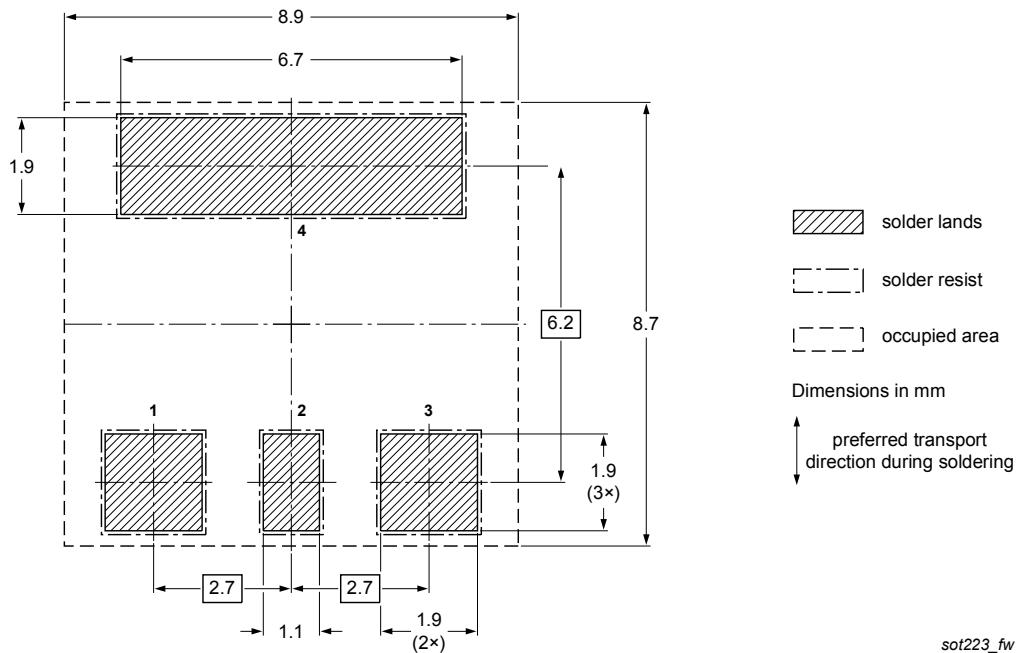


Fig. 16. Wave soldering footprint for SC-73 (SOT223)

12. Legal information

12.1 Data sheet status

Document status [1][2]	Product status [3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

- [1] Please consult the most recently issued document before initiating or completing a design.
- [2] The term 'short data sheet' is explained in section "Definitions".
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Date of release: 15 August 2014